FEB 1 0 2003

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

re the Application of: Yuji ONO et al.

Serial No.: 09/940,788

Filed: August 29, 2001

Group Art Unit: 1746

Examiner: Joseph L. Perrin

P.T.O. Confirmation No.: 4613

For: SINGLE WAFER TYPE SUBSTRATE CLEANING METHOD AND APPARATUS

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents Washington, D.C. 20231

February 10, 2003

Sir:

In response to the Office Action dated November 20, 2002, please amend the above-identified application as follows:

CLEAN VERSION OF AMENDMENTS

IN THE CLAIMS:

Please cancel claims 4-14 without prejudice or disclaimer.

Please amend claim 1 as follows:

1. (Amended) A single wafer type substrate cleaning method of wet-cleaned wafers which are not stored in a cassette, individually, in a sealed cleaning housing, said method consisting of the application of a spin drying treatment to the face of each wafer by supporting and rotating each wafer at high speed in the sealed cleaning housing while an inert gas for preventing oxidation is supplied to the face of the wafer in a drying step, where the amount of inert gas to be supplied to the face of each wafer is such that the amount of inert gas supplied at the outer peripheral portion is larger than that at the center thereof.

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